

THD200FI

HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- STMicroelectronics PREFERRED SALESTYPE
- HIGH VOLTAGE CAPABILITY
- VERY HIGH SWITCHING SPEED
- U.L. RECOGNISED ISOWATT218 PACKAGE (U.L. FILE # E81734 (N))

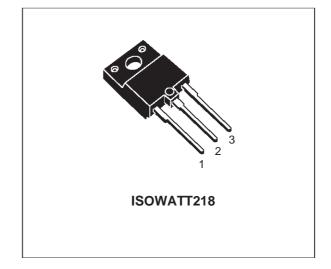
APPLICATIONS:

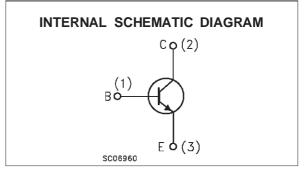
 HORIZONTAL DEFLECTION FOR MONITORS

DESCRIPTION

The THD200FI is manufactured using Multiepitaxial Mesa technology for cost-effective high performance and uses a Hollow Emitter structure to enhance switching speeds.

The THD series is designed for use in horizontal deflection circuits in televisions and monitors.





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V _{CBO}	Collector-Base Voltage (I _E = 0)	1500	V	
Vceo	Collector-Emitter Voltage (I _B = 0)	700	V	
V _{EBO}	Emitter-Base Voltage (I _C = 0)	10	V	
Ι _C	Collector Current	10	A	
I _{CM}	Collector Peak Current (t _p < 5 ms)	20	A	
Ι _Β	Base Current	5	A	
I _{BM}	Base Peak Current (t _p < 5 ms)	10	A	
P _{tot}	Total Dissipation at $T_c = 25 \ ^{\circ}C$	57	W	
T _{stg}	Storage Temperature	-65 to 150	°C	
Tj	Max. Operating Junction Temperature	150	°C	

December 1999

THERMAL DATA

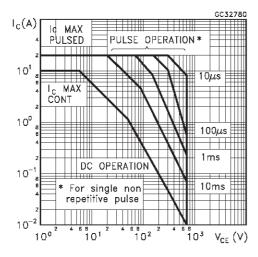
R _{thj-case} Thermal Resistance Junction-case N	Max 2.2	°C/W
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ELECTRICAL CHARACTERISTICS ($T_{case} = 25 \,^{\circ}C$ unless otherwise specified)

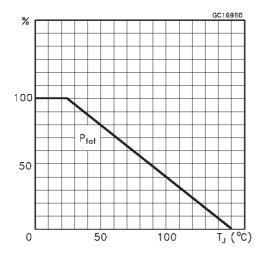
Symbol	Parameter	Parameter Test Conditions			Max.	Unit	
I _{CES}	Collector Cut-off Current ($V_{BE} = 0$)	$V_{CE} = 1500 V$ $V_{CE} = 1500 V$ $T_j = 125 °C$			0.2 2	mA mA	
I _{EBO}	Emitter Cut-off Current $(I_C = 0)$	$V_{EB} = 5 V$			100	μA	
$V_{CEO(sus)}^*$	Collector-Emitter Sustaining Voltage (I _C = 0)	Ic = 100 mA	700			V	
V_{EBO}	Emitter-Base Voltage (I _B = 0)	I _E = 10 mA	10			V	
V _{CE(sat)} *	Collector-Emitter Saturation Voltage	$I_{C} = 7 A I_{B} = 1.5 A$			1.5	V	
$V_{\text{BE}(\text{sat})}*$	Base-Emitter Saturation Voltage	$I_{\rm C} = 7 \ {\rm A}$ $I_{\rm B} = 1.5 \ {\rm A}$			1.3	V	
h _{FE} *	DC Current Gain		6.5 4		13		
t _s t _f	RESISTIVE LOAD Storage Time Fall Time			2.1 140	3.1 210	μs ns	
t _s t _f	INDUCTIVE LOAD Storage Time Fall Time	$ I_{C} = 7 A \qquad f = 31250 \text{ Hz} \\ I_{B1} = 1.5 A \qquad I_{B2} = -3.5 \text{ A} \\ V_{ceflyback} = 1200 \ sin \left(\frac{\pi}{5} \ 10^{6}\right) t V $		3.5 320		μs ns	
t _s t _f	5			1.7 215		μs ns	

* Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

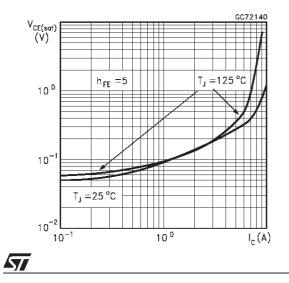
Safe Operating Area



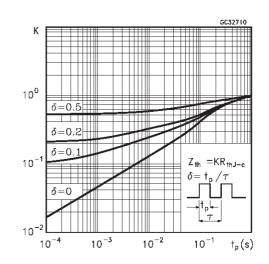
Derating Curve



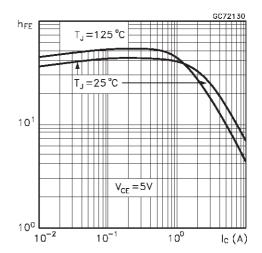
Collector Emitter Saturation Voltage



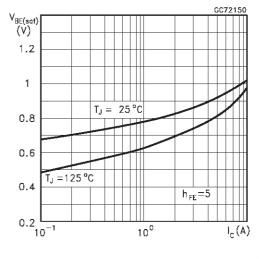
Thermal Impedance



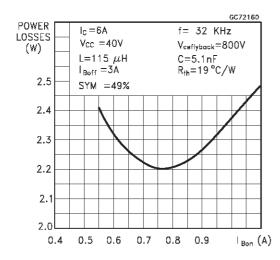




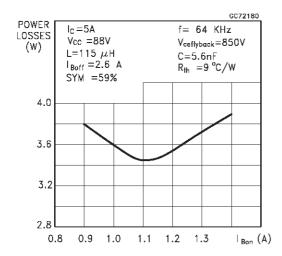




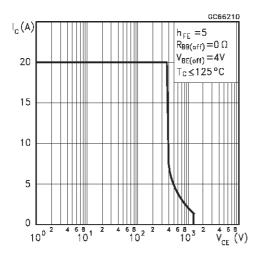
Power Losses at 32 KHz



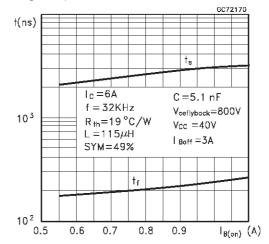
Power Losses at 64 KHz



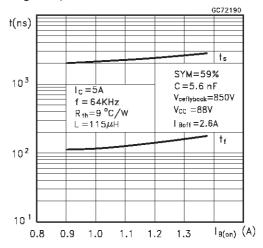




Switching Time Inductive Load at 32 KHz (see figure 2)



Switching Time Inductive Load at 64 KHz (see figure 2)



BASE DRIVE INFORMATION

In order to saturate the power switch and reduce conduction losses, adequate direct base current I_{B1} has to be provided for the lowest gain h_{FE} at T_j = 100 °C (line scan phase). On the other hand, negative base current I_{B2} must be provided turn off the power transistor (retrace phase). Most of the dissipation, especially in the deflection application, occurs at switch-off so it is essential to determine the value of I_{B2} which minimizes power losses, fall time t_f and, consequently, T_j . A new set of curves have been defined to give total power losses, t_s and t_f as a function of I_{B2} at both 32 KHz and 64 KHz scanning frequencies in order to choice the optimum negative drive. The test circuit is illustrated in fig. 1.

Figure 1: Inductive Load Switching Test Circuit.

Inductance L_1 serves to control the slope of the negative base current I_{B2} in order to recombine the excess carriers in the collector when base current is still present, thus avoiding any tailing phenomenon in the collector current.

The values of L and C are calculated from the following equations:

$$\frac{1}{2} L (I_C)^2 = \frac{1}{2} C (V_{CEfly})^2$$

w = 2 \pi f = $\frac{1}{\sqrt{L C}}$

Where I_C = operating collector current, V_{CEfly} = flyback voltage, f= frequency of oscillation during retrace.

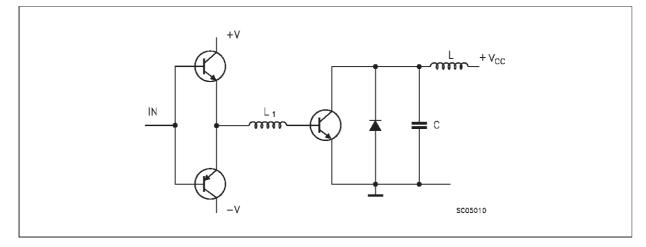
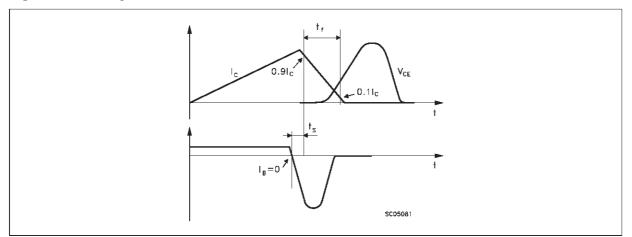


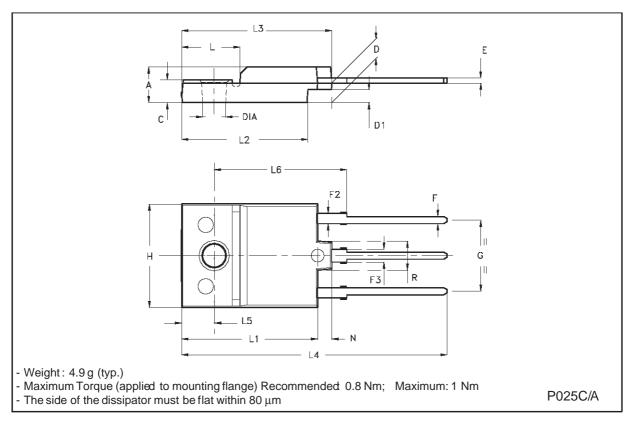
Figure 2: Switching Waveforms in a Deflection Circuit.



THD200FI

ISOWATT218 MECHANICAL DAT	۲A
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DIM	mm			inch		
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	5.35		5.65	0.211		0.222
С	3.30		3.80	0.130		0.150
D	2.90		3.10	0.114		0.122
D1	1.88		2.08	0.074		0.082
E	0.75		0.95	0.030		0.037
F	1.05		1.25	0.041		0.049
F2	1.50		1.70	0.059		0.067
F3	1.90		2.10	0.075		0.083
G	10.80		11.20	0.425		0.441
Н	15.80		16.20	0.622		0.638
L		9			0.354	
L1	20.80		21.20	0.819		0.835
L2	19.10		19.90	0.752		0.783
L3	22.80		23.60	0.898		0.929
L4	40.50		42.50	1.594		1.673
L5	4.85		5.25	0.191		0.207
L6	20.25		20.75	0.797		0.817
Ν	2.1		2.3	0.083		0.091
R		4.6			0.181	
DIA	3.5		3.7	0.138		0.146



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